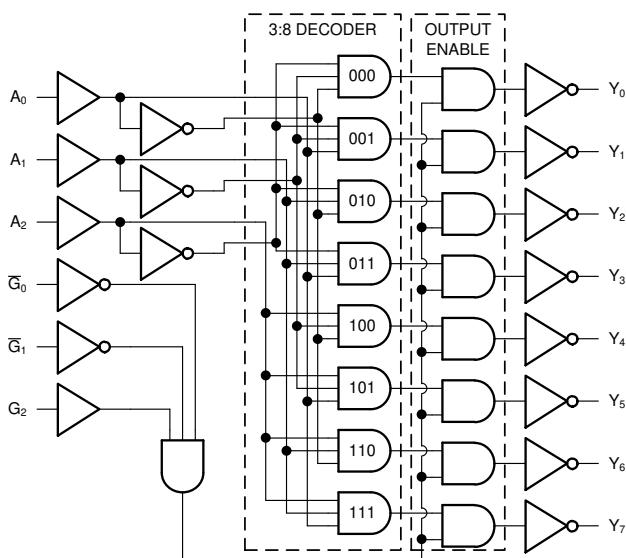


CDx4HC138, CDx4HCT138, CDx4HC238, CDx4HCT238 High-Speed CMOS Logic 3- to 8-Line Decoder/Demultiplexer Inverting and Noninverting

1 Features

- Select one of eight data outputs:
 - Active low for '138
 - Active high for '238
- I/O port or memory selector
- Three enable inputs to simplify cascading
- Typical propagation delay of 13 ns at $V_{CC} = 5$ V, $C_L = 15$ pF, $T_A = 25^\circ\text{C}$
- Fanout (over temperature range)
 - Bus driver outputs: 15 LSTTL loads
 - Standard outputs: 10 LSTTL loads
- Wide operating temp range: -55°C to 125°C
- Balanced propagation delay and transition times
- Significant power reduction compared to LSTTL logic ICs
- HC types
 - 2 V to 6 V operation
 - High noise immunity: $N_{IL} = 30\%$, $N_{IH} = 30\%$ of V_{CC} at $V_{CC} = 5$ V
- HCT types
 - 4.5-V to 5.5-V operation
 - Direct LSTTL input logic compatibility, $V_{IL} = 0.8$ V (Max), $V_{IH} = 2$ V (Min)
 - CMOS input compatibility, $I_I \leq 1\mu\text{A}$ at V_{OL}, V_{OH}



Functional Block Diagram '138

2 Description

The CDx4HC(T)138 and '238 are three to eight decoders with one standard output strobe (G_2) and two active low output strobes (\bar{G}_1 and \bar{G}_0). When the outputs are gated by any of the strobe inputs, they are all forced into the high state. When the outputs are not disabled by the strobe inputs, only the selected output is low while all others are high.

The CDx4HC(T)238 is a three to eight decoder with one standard output strobe (G_2) and two active low output strobes (\bar{G}_1 and \bar{G}_0). When the outputs are gated by any of the strobe inputs, they are all forced into the low state. When the outputs are not disabled by the strobe inputs, only the selected output is high while all others are low.

Device Information

| PART NUMBER | PACKAGE ⁽¹⁾ | BODY SIZE (NOM) |
|--------------|------------------------|--------------------|
| CD74HC138E | PDIP (16) | 25.40 mm × 6.35 mm |
| CD74HCT138E | PDIP (16) | 25.40 mm × 6.35 mm |
| CD74HCT238E | PDIP (16) | 25.40 mm × 6.35 mm |
| CD74HC138M | SOIC (16) | 9.90 mm × 3.90 mm |
| CD74HCT238M | SOIC (16) | 9.90 mm × 3.90 mm |
| CD74HC238NS | SO (16) | 10.20 mm × 5.30 mm |
| CD74HC238PW | TSSOP (16) | 5.00 mm × 4.40 mm |
| CD74HCT238PW | TSSOP (16) | 5.00 mm × 4.40 mm |
| CD54HC138F | CDIP (16) | 21.34 mm × 6.92 mm |
| CD54HCT138F | CDIP (16) | 21.34 mm × 6.92 mm |
| CD54HCT238F | CDIP (16) | 21.34 mm × 6.92 mm |

(1) For all available packages, see the orderable addendum at the end of the data sheet.



An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

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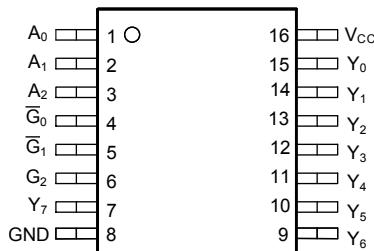
| | | | |
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3 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

| Changes from Revision I (August 2004) to Revision J (November 2021) | Page |
|---|-------------|
| • Updated the numbering, formatting, tables, figures, and cross-references throughout the document to reflect modern datasheet standards..... | 1 |
| • Updated pin names to match current TI naming conventions. E ₃ is now G ₂ , E ₂ is now G ₁ , E ₁ is now G ₀ | 1 |

4 Pin Configuration and Functions



**J, N, D, NS, or PW package
16-Pin CDIP, PDIP, SOIC, SO, or TSSOP
Top View**

Pin Functions

| PIN | | I/O ⁽¹⁾ | DESCRIPTION |
|-------------------|-----------------|--------------------|-----------------------------|
| SOIC or TSSOP NO. | NAME | | |
| 1 | A ₀ | I | Address select 0 |
| 2 | A ₁ | I | Address select 1 |
| 3 | A ₂ | I | Address select 2 |
| 4 | ̄G ₀ | I | Output strobe 0, active low |
| 5 | ̄G ₁ | I | Output strobe 1, active low |
| 6 | G ₂ | I | Output strobe 2 |
| 7 | Y ₇ | O | Output 7 |
| 8 | GND | — | Ground |
| 9 | Y ₆ | O | Output 6 |
| 10 | Y ₅ | O | Output 5 |
| 11 | Y ₄ | O | Output 4 |
| 12 | Y ₃ | O | Output 3 |
| 13 | Y ₂ | O | Output 2 |
| 14 | Y ₁ | O | Output 1 |
| 15 | Y ₀ | O | Output 0 |
| 16 | V _{CC} | — | Positive supply |

(1) Signal Types: I = Input, O = Output, I/O = Input or Output.

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

| | | | MIN | MAX | UNIT |
|------------------|--|---|------|-----|------|
| V _{CC} | Supply voltage | | -0.5 | 7 | V |
| I _{IK} | Input clamp diode current | For V _I < 0.5V or V _I > V _{CC} + 0.5V | | ±20 | mA |
| I _{OK} | Output clamp diode current | For V _O < -0.5V or V _O > V _{CC} + 0.5V | | ±20 | mA |
| I _O | Output source or sink current per output pin | For V _O > -0.5V or V _O < V _{CC} + 0.5V | | ±25 | mA |
| | Continuous current through V _{CC} or GND | | | ±50 | mA |
| T _J | Junction temperature | | | 150 | °C |
| T _{stg} | Storage temperature range | | -65 | 150 | °C |
| | Lead temperature (Soldering 10s) (SOIC - Lead Tips Only) | | | 300 | °C |

(1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

5.2 Recommended Operating Conditions

| | | | MIN | MAX | UNIT |
|-----------------|--------------------------|------------------------|-----|-----------------|------|
| V _{CC} | Supply voltage range | HC types | 2 | 6 | V |
| | | HCT types | 4.5 | 5.5 | |
| V _I | Input voltage | | 0 | V _{CC} | V |
| V _O | Output voltage | | 0 | V _{CC} | V |
| t _l | Input rise and fall time | V _{CC} = 2V | | 1000 | ns |
| | | V _{CC} = 4.5V | | 500 | |
| | | V _{CC} = 6V | | 400 | |
| T _A | Temperature range | | -55 | 125 | °C |

5.3 Thermal Information

| THERMAL METRIC | | CD74HC(T)138, CD74HC(T)238 | | | | UNIT |
|------------------|---|----------------------------|-------------|-------------|---------------|------|
| | | N (PDIP) | D (SOIC) | NS (SOP) | PW (TSSOP) | |
| | | 16 Pins | 16 Pins | 16 Pins | 16 Pins | |
| R _{θJA} | Junction-to-ambient thermal resistance ⁽¹⁾ | 67 | 73 | 64 | 108 | °C/W |

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC package thermal metrics](#) application report.

5.4 Electrical Characteristics

| PARAMETER | TEST CONDITIONS ⁽¹⁾ | V _{CC} (V) | 25°C | | | -40°C to 85°C | | -55°C to 125°C | | UNIT |
|------------------|---|--|------------|------|------|---------------|-------|----------------|-------|------|
| | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| HC TYPES | | | | | | | | | | |
| V _{IH} | High-level input voltage | | 2 | 1.5 | | 1.5 | | 1.5 | | V |
| | | | 4.5 | 3.15 | | 3.15 | | 3.15 | | V |
| | | | 6 | 4.2 | | 4.2 | | 4.2 | | V |
| V _{IL} | Low-level input voltage | | 2 | | 0.5 | | 0.5 | | 0.5 | V |
| | | | 4.5 | | 1.35 | | 1.35 | | 1.35 | V |
| | | | 6 | | 1.8 | | 1.8 | | 1.8 | V |
| V _{OH} | High-level output voltage | I _{OH} = -20 µA | 2 | 1.9 | | 1.9 | | 1.9 | | V |
| | | I _{OH} = -20 µA | 4.5 | 4.4 | | 4.4 | | 4.4 | | V |
| | | I _{OH} = -20 µA | 6 | 5.9 | | 5.9 | | 5.9 | | V |
| | High-level output voltage | I _{OH} = -4 mA | 4.5 | 3.98 | | 3.84 | | 3.7 | | V |
| | | I _{OH} = -5.2 mA | 6 | 5.48 | | 5.34 | | 5.2 | | V |
| V _{OL} | Low-level output voltage | I _{OL} = 20 µA | 2 | | 0.1 | | 0.1 | | 0.1 | V |
| | | I _{OL} = 20 µA | 4.5 | | 0.1 | | 0.1 | | 0.1 | V |
| | | I _{OL} = 20 µA | 6 | | 0.1 | | 0.1 | | 0.1 | V |
| | Low-level output voltage | I _{OL} = 4 mA | 4.5 | | 0.26 | | 0.33 | | 0.4 | V |
| | | I _{OL} = 5.2 mA | 6 | | 0.26 | | 0.33 | | 0.4 | V |
| I _I | Input leakage current | V _I = V _{CC} or GND | 6 | | ±0.1 | | ±1 | | ±1 | µA |
| I _{CC} | Supply current | V _I = V _{CC} or GND | 6 | | 8 | | 80 | | 160 | µA |
| HCT TYPES | | | | | | | | | | |
| V _{IH} | High-level input voltage | | 4.5 to 5.5 | 2 | | 2 | | 2 | | V |
| V _{IL} | Low-level input voltage | | 4.5 to 5.5 | | 0.8 | | 0.8 | | 0.8 | V |
| V _{OH} | High-level output voltage | I _{OH} = -20 µA | 4.5 | 4.4 | | 4.4 | | 4.4 | | V |
| | High-level output voltage | I _{OH} = -4 mA | 4.5 | 3.98 | | 3.84 | | 3.7 | | V |
| V _{OL} | Low-level output voltage | I _{OL} = 20 µA | 4.5 | | 0.1 | | 0.1 | | 0.1 | V |
| | Low-level output voltage | I _{OH} = 4 mA | 4.5 | | 0.26 | | 0.33 | | 0.4 | V |
| I _I | Input leakage current | V _I = V _{CC} and GND | 5.5 | | ±0.1 | | ±1 | | ±1 | µA |
| I _{CC} | Supply current | V _I = V _{CC} and GND | 5.5 | | 8 | | 80 | | 160 | µA |
| ΔI _{CC} | Additional supply current per input pin | A ₀ - A ₂ inputs held at V _{CC} - 2.1 V | 4.5 to 5.5 | 100 | 540 | | 675 | | 735 | µA |
| | | ̄G ₀ and ̄G ₁ inputs held at V _{CC} - 2.1 V | 4.5 to 5.5 | 100 | 450 | | 562.5 | | 612.5 | µA |
| | | G ₂ input held at V _{CC} - 2.1 V | 4.5 to 5.5 | 100 | 360 | | 450 | | 490 | µA |

(1) V_I = V_{IH} or V_{IL}, unless otherwise noted.

5.5 Switching Characteristics ⁽²⁾

Input t_l = 6ns. (See [Parameter Measurement Information](#))

| PARAMETER | TEST CONDITIONS | V_{CC} (V) | 25°C | | | -40°C to 85°C | | -55°C to 125°C | | UNIT |
|------------------|---|--------------|------|-----|-------------------|---------------|-----|----------------|-----|-------|
| | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| HC TYPES | | | | | | | | | | |
| t_{pd} | Address to output | C_L = 50pF | 2 | | 150 | | 190 | | 225 | ns |
| | | | 4.5 | | 13 ⁽³⁾ | 30 | | 38 | | |
| | | C_L = 50pF | 6 | | 26 | | 33 | | 38 | |
| | Strobe \overline{G}_0 , \overline{G}_1 , G_2 to output HC/HCT 138 | C_L = 50pF | 2 | | 150 | | 190 | | 265 | ns |
| | | | 4.5 | | 30 | | 38 | | 53 | |
| | | | 6 | | 26 | | 33 | | 45 | |
| t_l | Output transition time | C_L = 50pF | 2 | | 75 | | 95 | | 110 | MHz |
| | | | 4.5 | | 15 | | 19 | | 22 | |
| | | | 6 | | 13 | | 16 | | 19 | |
| C_{pd} | Power dissipation capacitance ⁽¹⁾ | C_L = 15pF | 5 | | 67 | | | | | pF |
| C_i | Input capacitance | | | | | 10 | | 10 | | 10 pF |
| HCT TYPES | | | | | | | | | | |
| t_{pd} | Address to output | C_L = 50pF | 4.5 | | 14 ⁽³⁾ | 35 | | 44 | | 53 ns |
| | Strobe G_2 to output HC/HCT138 | C_L = 50pF | 4.5 | | 35 | | 44 | | 53 | ns |
| | Strobe \overline{G}_0 , \overline{G}_1 to output HC/HCT238 | C_L = 15pF | 4.5 | | 40 | | 50 | | 60 | ns |
| t_l | Output transition time | C_L = 15pF | 4.5 | | 15 | | 19 | | 22 | |
| C_{pd} | Power dissipation capacitance ⁽¹⁾ | C_L = 15pF | 5 | | 67 | | | | | pF |
| C_i | Input capacitance | | | | | 10 | | 10 | | 10 pF |

(1) C_{PD} is used to determine the dynamic power consumption, per gate.

(2) For details on power calculation, see [SCAA035B](#)

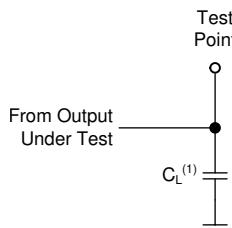
(3) C_L = 15pF and V_{CC} = 5

6 Parameter Measurement Information

Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_t < 6$ ns.

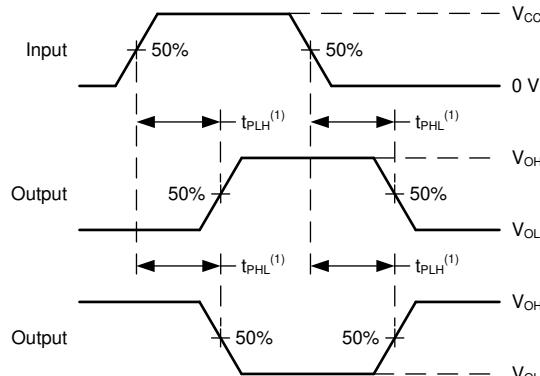
For clock inputs, f_{max} is measured when the input duty cycle is 50%.

The outputs are measured one at a time with one input transition per measurement.



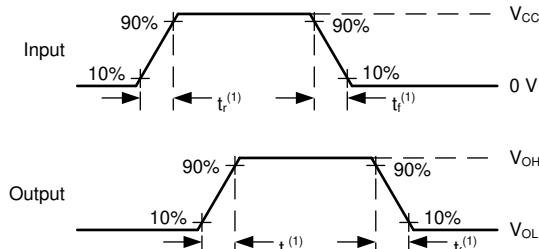
(1) C_L includes probe and test-fixture capacitance.

Figure 6-1. Load Circuit for Push-Pull Outputs



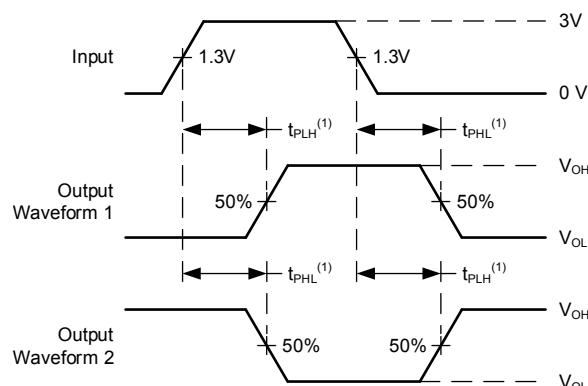
(1) The greater between t_{PLH} and t_{PHL} is the same as t_{pd} .

Figure 6-2. Voltage Waveforms, Propagation Delays for Standard CMOS Inputs



(1) The greater between t_r and t_f is the same as t_t .

Figure 6-3. Voltage Waveforms, Input and Output Transition Times for Standard CMOS Inputs



(1) The greater between t_{PLH} and t_{PHL} is the same as t_{pd} .

Figure 6-4. Voltage Waveforms, Propagation Delays for TTL-Compatible Inputs

7 Detailed Description

7.1 Overview

The CDx4HC(T)138 and '238 are high speed silicon gate CMOS decoders well suited to memory address decoding or data routing applications. They contain a single 3:8 decoder.

The CDx4HC(T)138 and '238 have three address select inputs (A_2 , A_1 , and A_0). The circuit functions as a normal one-of-eight decoder.

Three strobe inputs (G_2 , \bar{G}_1 and \bar{G}_0) are provided to simplify cascading and to facilitate demultiplexing. When any input strobe is active, all outputs are forced into the high state for the '138 function. When any input strobe is active, all outputs are forced into the low state for the '238 function.

The demultiplexing function is accomplished by first using the select inputs to choose the desired output, and then using one of the strobe inputs as the data input.

The outputs for the CDx4HC(T)138 are normally low when selected. The outputs for the CDxHC(T)238 are normally high when selected.

7.2 Functional Block Diagram

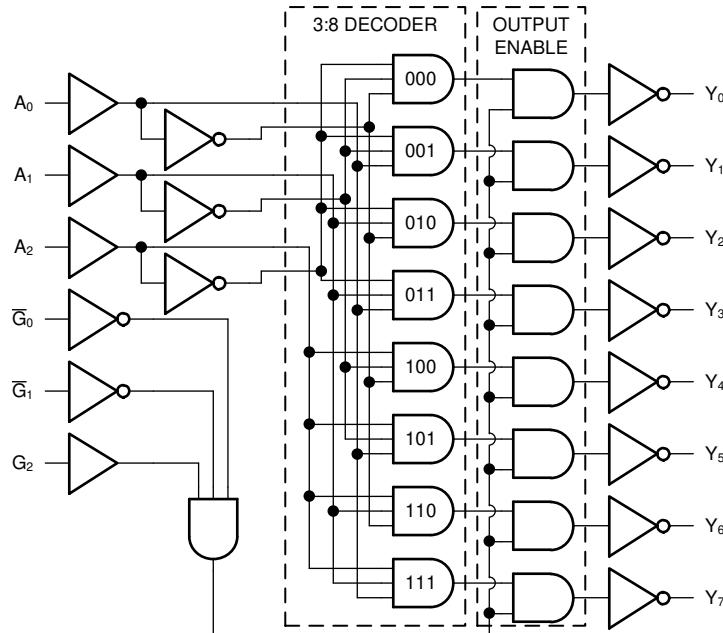


Figure 7-1. Functional Block Diagram '138

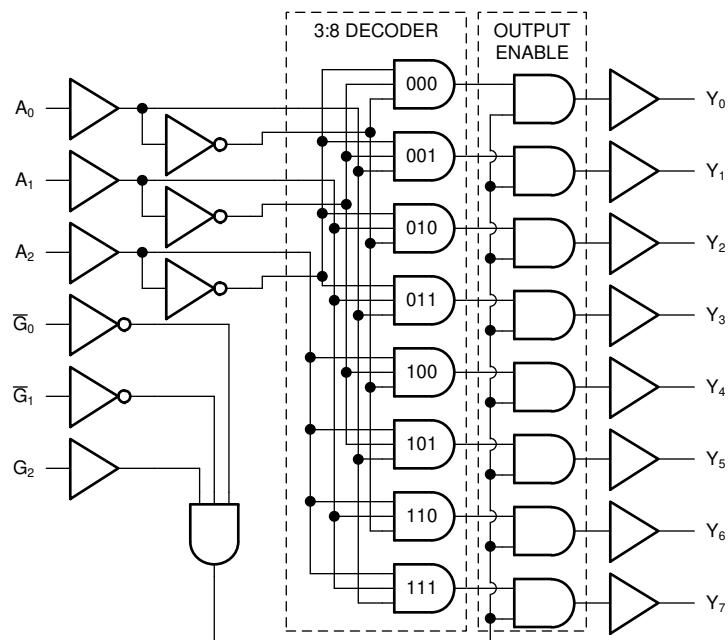


Figure 7-2. Functional Block Diagram '238

7.3 Device Functional Modes

Table 7-1. Function Table 'HC138, 'HCT138

| INPUTS | | | | | | OUTPUTS | | | | | | | |
|--------|------------------|------------------|---------|-------|-------|---------|-------|-------|-------|-------|-------|-------|-------|
| STROBE | | | ADDRESS | | | Y_0 | Y_1 | Y_2 | Y_3 | Y_4 | Y_5 | Y_6 | Y_7 |
| G_2 | $\overline{G_1}$ | $\overline{G_0}$ | A_2 | A_1 | A_0 | | | | | | | | |
| X | X | H | X | X | X | H | H | H | H | H | H | H | H |
| L | X | X | X | X | X | H | H | H | H | H | H | H | H |
| X | H | X | X | X | X | H | H | H | H | H | H | H | H |
| H | L | L | L | L | L | L | H | H | H | H | H | H | H |
| H | L | L | L | L | H | H | L | H | H | H | H | H | H |
| H | L | L | L | H | L | H | H | L | H | H | H | H | H |
| H | L | L | H | L | L | H | H | H | L | H | H | H | H |
| H | L | L | H | L | H | H | H | H | H | L | H | H | H |
| H | L | L | H | H | H | H | H | H | H | H | H | L | H |
| H | L | L | H | H | H | H | H | H | H | H | H | H | L |

H = High Voltage Level, L = Low Voltage Level, X = Don't Care

Table 7-2. Function Table 'HC238, 'HCT238

| INPUTS | | | | | | OUTPUTS | | | | | | | |
|--------|------------------|------------------|---------|-------|-------|---------|-------|-------|-------|-------|-------|-------|-------|
| STROBE | | | ADDRESS | | | Y_0 | Y_1 | Y_2 | Y_3 | Y_4 | Y_5 | Y_6 | Y_7 |
| G_2 | $\overline{G_1}$ | $\overline{G_0}$ | A_2 | A_1 | A_0 | | | | | | | | |
| X | X | H | X | X | X | L | L | L | L | L | L | L | L |
| L | X | X | X | X | X | L | L | L | L | L | L | L | L |
| X | H | X | X | X | X | L | L | L | L | L | L | L | L |
| H | L | L | L | L | L | H | L | L | L | L | L | L | L |
| H | L | L | L | L | H | L | H | L | L | L | L | L | L |
| H | L | L | L | H | L | L | L | H | L | L | L | L | L |
| H | L | L | L | H | H | L | L | L | H | L | L | L | L |
| H | L | L | H | L | L | L | L | L | L | H | L | L | L |
| H | L | L | H | L | H | L | L | L | L | L | H | L | L |
| H | L | L | H | H | L | L | L | L | L | L | L | H | L |
| H | L | L | H | H | H | L | L | L | L | L | L | L | H |

H = High Voltage Level, L = Low Voltage Level, X = Don't Care

8 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the *Recommended Operating Conditions*. Each V_{CC} terminal should have a good bypass capacitor to prevent power disturbance. A 0.1- μ F capacitor is recommended for this device. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. The 0.1- μ F and 1- μ F capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results.

9 Layout

9.1 Layout Guidelines

When using multiple-input and multiple-channel logic devices inputs must not ever be left floating. In many cases, functions or parts of functions of digital logic devices are unused; for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such unused input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. All unused inputs of digital logic devices must be connected to a logic high or logic low voltage, as defined by the input voltage specifications, to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally, the inputs are tied to GND or V_{CC} , whichever makes more sense for the logic function or is more convenient.

10 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

10.1 Documentation Support

10.1.1 Related Documentation

10.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

10.3 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

10.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

All trademarks are the property of their respective owners.

10.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

10.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

| Orderable part number | Status (1) | Material type (2) | Package Pins | Package qty Carrier | RoHS (3) | Lead finish/ Ball material (4) | MSL rating/ Peak reflow (5) | Op temp (°C) | Part marking (6) |
|-----------------------|---------------|----------------------|----------------|-----------------------|-------------|--------------------------------------|-----------------------------------|--------------|---------------------------------|
| 5962-8688401EA | Active | Production | CDIP (J) 16 | 25 TUBE | No | SNPB | N/A for Pkg Type | -55 to 125 | 5962-8688401EA CD54HC238F3A |
| CD54HC138F | Active | Production | CDIP (J) 16 | 25 TUBE | No | SNPB | N/A for Pkg Type | -55 to 125 | CD54HC138F |
| CD54HC138F.A | Active | Production | CDIP (J) 16 | 25 TUBE | No | SNPB | N/A for Pkg Type | -55 to 125 | CD54HC138F |
| CD54HC138F3A | Active | Production | CDIP (J) 16 | 25 TUBE | No | SNPB | N/A for Pkg Type | -55 to 125 | 8406201EA CD54HC138F3A |
| CD54HC138F3A.A | Active | Production | CDIP (J) 16 | 25 TUBE | No | SNPB | N/A for Pkg Type | -55 to 125 | 8406201EA CD54HC138F3A |
| CD54HC238F3A | Active | Production | CDIP (J) 16 | 25 TUBE | No | SNPB | N/A for Pkg Type | -55 to 125 | 5962-8688401EA CD54HC238F3A |
| CD54HC238F3A.A | Active | Production | CDIP (J) 16 | 25 TUBE | No | SNPB | N/A for Pkg Type | -55 to 125 | 5962-8688401EA CD54HC238F3A |
| CD54HCT138F | Active | Production | CDIP (J) 16 | 25 TUBE | No | SNPB | N/A for Pkg Type | -55 to 125 | CD54HCT138F |
| CD54HCT138F.A | Active | Production | CDIP (J) 16 | 25 TUBE | No | SNPB | N/A for Pkg Type | -55 to 125 | CD54HCT138F |
| CD54HCT138F3A | Active | Production | CDIP (J) 16 | 25 TUBE | No | SNPB | N/A for Pkg Type | -55 to 125 | 8550401EA CD54HCT138F3A |
| CD54HCT138F3A.A | Active | Production | CDIP (J) 16 | 25 TUBE | No | SNPB | N/A for Pkg Type | -55 to 125 | 8550401EA CD54HCT138F3A |
| CD54HCT238F3A | Active | Production | CDIP (J) 16 | 25 TUBE | No | SNPB | N/A for Pkg Type | -55 to 125 | 5962-8974501EA CD54HCT238F3A |
| CD54HCT238F3A.A | Active | Production | CDIP (J) 16 | 25 TUBE | No | SNPB | N/A for Pkg Type | -55 to 125 | 5962-8974501EA CD54HCT238F3A |
| CD74HC138E | Active | Production | PDIP (N) 16 | 25 TUBE | Yes | NIPDAU | N/A for Pkg Type | -55 to 125 | CD74HC138E |
| CD74HC138E.A | Active | Production | PDIP (N) 16 | 25 TUBE | Yes | NIPDAU | N/A for Pkg Type | -55 to 125 | CD74HC138E |
| CD74HC138M | Obsolete | Production | SOIC (D) 16 | - | - | Call TI | Call TI | -55 to 125 | HC138M |
| CD74HC138M96 | Active | Production | SOIC (D) 16 | 2500 LARGE T&R | Yes | NIPDAU SN | Level-1-260C-UNLIM | -55 to 125 | HC138M |
| CD74HC138M96.A | Active | Production | SOIC (D) 16 | 2500 LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HC138M |
| CD74HC138M96E4 | Active | Production | null (null) | 2500 LARGE T&R | - | Call TI | Call TI | -55 to 125 | |
| CD74HC138M96G4 | Active | Production | SOIC (D) 16 | 2500 LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HC138M |
| CD74HC138M96G4.A | Active | Production | SOIC (D) 16 | 2500 LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HC138M |
| CD74HC138MT | Obsolete | Production | SOIC (D) 16 | - | - | Call TI | Call TI | -55 to 125 | HC138M |

| Orderable part number | Status (1) | Material type (2) | Package Pins | Package qty Carrier | RoHS (3) | Lead finish/ Ball material (4) | MSL rating/ Peak reflow (5) | Op temp (°C) | Part marking (6) |
|---------------------------------|---------------|----------------------|-----------------|-----------------------|-------------|--------------------------------------|-----------------------------------|--------------|---------------------|
| CD74HC238E | Active | Production | PDIP (N) 16 | 25 TUBE | Yes | NIPDAU | N/A for Pkg Type | -55 to 125 | CD74HC238E |
| CD74HC238E.A | Active | Production | PDIP (N) 16 | 25 TUBE | Yes | NIPDAU | N/A for Pkg Type | -55 to 125 | CD74HC238E |
| CD74HC238EE4 | Active | Production | PDIP (N) 16 | 25 TUBE | Yes | NIPDAU | N/A for Pkg Type | -55 to 125 | CD74HC238E |
| CD74HC238M | Obsolete | Production | SOIC (D) 16 | - | - | Call TI | Call TI | -55 to 125 | HC238M |
| CD74HC238M96 | Active | Production | SOIC (D) 16 | 2500 LARGE T&R | Yes | NIPDAU SN | Level-1-260C-UNLIM | -55 to 125 | HC238M |
| CD74HC238M96.A | Active | Production | SOIC (D) 16 | 2500 LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HC238M |
| CD74HC238M961G4 | Active | Production | SOIC (D) 16 | 2500 LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HC238M |
| CD74HC238M961G4.A | Active | Production | SOIC (D) 16 | 2500 LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HC238M |
| CD74HC238MT | Obsolete | Production | SOIC (D) 16 | - | - | Call TI | Call TI | -55 to 125 | HC238M |
| CD74HC238NSR | Active | Production | SOP (NS) 16 | 2000 LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HC238M |
| CD74HC238NSR.A | Active | Production | SOP (NS) 16 | 2000 LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HC238M |
| CD74HC238PW | Obsolete | Production | TSSOP (PW) 16 | - | - | Call TI | Call TI | -55 to 125 | HJ238 |
| CD74HC238PWR | Active | Production | TSSOP (PW) 16 | 2000 LARGE T&R | Yes | NIPDAU SN | Level-1-260C-UNLIM | -55 to 125 | HJ238 |
| CD74HC238PWR.A | Active | Production | TSSOP (PW) 16 | 2000 LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HJ238 |
| CD74HC238PWR1G4 | Active | Production | TSSOP (PW) 16 | 2000 LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HJ238 |
| CD74HC238PWT | Obsolete | Production | TSSOP (PW) 16 | - | - | Call TI | Call TI | -55 to 125 | HJ238 |
| CD74HCT138E | Active | Production | PDIP (N) 16 | 25 TUBE | Yes | NIPDAU | N/A for Pkg Type | -55 to 125 | CD74HCT138E |
| CD74HCT138E.A | Active | Production | PDIP (N) 16 | 25 TUBE | Yes | NIPDAU | N/A for Pkg Type | -55 to 125 | CD74HCT138E |
| CD74HCT138M | Obsolete | Production | SOIC (D) 16 | - | - | Call TI | Call TI | -55 to 125 | HCT138M |
| CD74HCT138M96 | Active | Production | SOIC (D) 16 | 2500 LARGE T&R | Yes | NIPDAU SN | Level-1-260C-UNLIM | -55 to 125 | HCT138M |
| CD74HCT138M96.A | Active | Production | SOIC (D) 16 | 2500 LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HCT138M |
| CD74HCT238E | Active | Production | PDIP (N) 16 | 25 TUBE | Yes | NIPDAU | N/A for Pkg Type | -55 to 125 | CD74HCT238E |
| CD74HCT238E.A | Active | Production | PDIP (N) 16 | 25 TUBE | Yes | NIPDAU | N/A for Pkg Type | -55 to 125 | CD74HCT238E |
| CD74HCT238M | Obsolete | Production | SOIC (D) 16 | - | - | Call TI | Call TI | -55 to 125 | HCT238M |
| CD74HCT238M96 | Active | Production | SOIC (D) 16 | 2500 LARGE T&R | Yes | NIPDAU SN | Level-1-260C-UNLIM | -55 to 125 | HCT238M |
| CD74HCT238M96.A | Active | Production | SOIC (D) 16 | 2500 LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HCT238M |
| CD74HCT238PW | Obsolete | Production | TSSOP (PW) 16 | - | - | Call TI | Call TI | -55 to 125 | HK238 |
| CD74HCT238PWR | Active | Production | TSSOP (PW) 16 | 2000 LARGE T&R | Yes | NIPDAU SN | Level-1-260C-UNLIM | -55 to 125 | HK238 |
| CD74HCT238PWR.A | Active | Production | TSSOP (PW) 16 | 2000 LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HK238 |

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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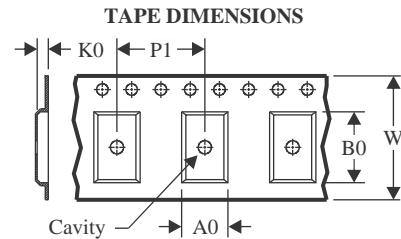
OTHER QUALIFIED VERSIONS OF CD54HC138, CD54HC238, CD54HCT138, CD54HCT238, CD74HC138, CD74HC238, CD74HCT138, CD74HCT238 :

- Catalog : [CD74HC138](#), [CD74HC238](#), [CD74HCT138](#), [CD74HCT238](#)
- Automotive : [CD74HC138-Q1](#), [CD74HC138-Q1](#)
- Military : [CD54HC138](#), [CD54HC238](#), [CD54HCT138](#), [CD54HCT238](#)

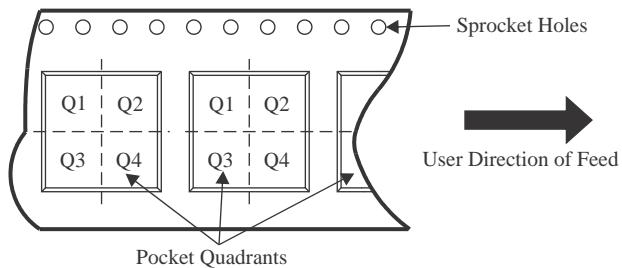
NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Military - QML certified for Military and Defense Applications

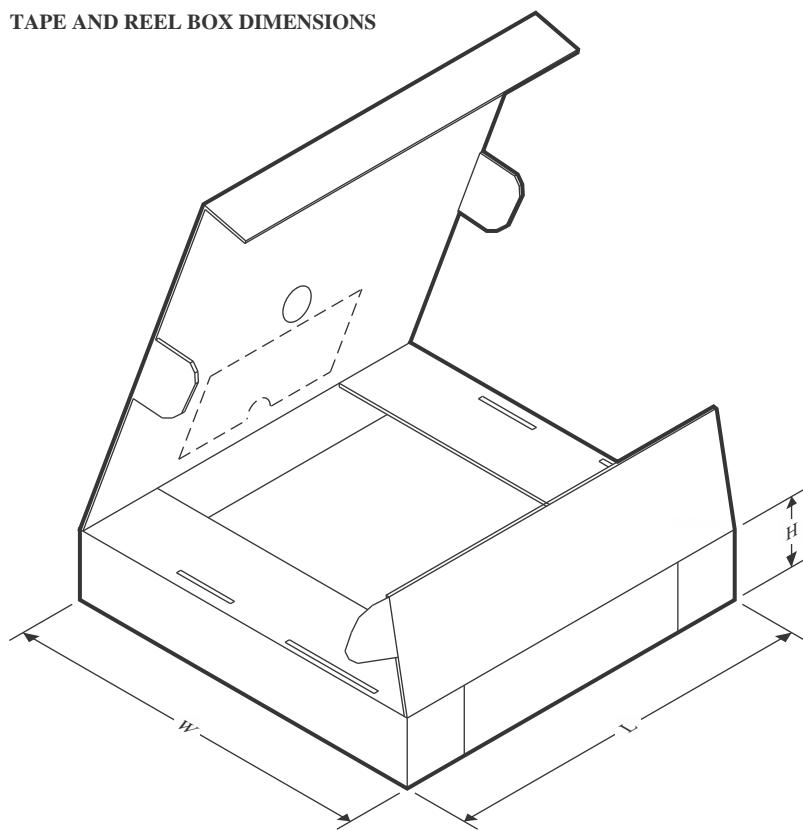
TAPE AND REEL INFORMATION


| | |
|----|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


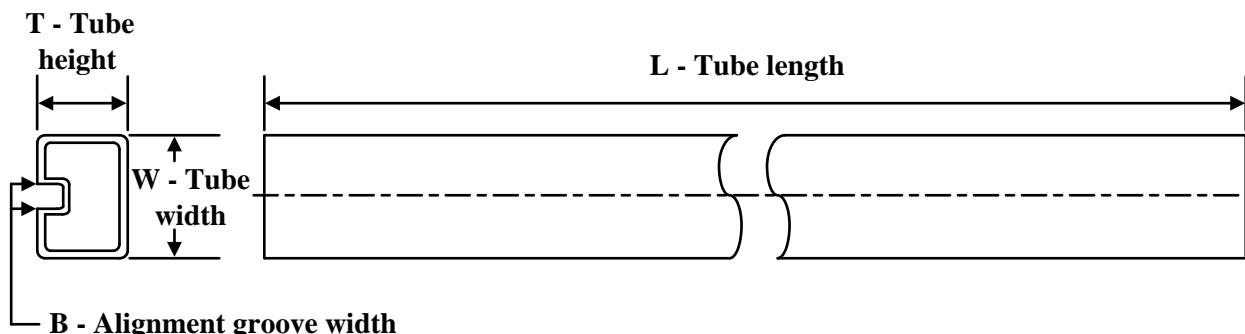
*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-----------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| CD74HC138M96 | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |
| CD74HC138M96G4 | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |
| CD74HC238M96 | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |
| CD74HC238M96 | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |
| CD74HC238M961G4 | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |
| CD74HC238NSR | SOP | NS | 16 | 2000 | 330.0 | 16.4 | 8.1 | 10.4 | 2.5 | 12.0 | 16.0 | Q1 |
| CD74HC238PWR | TSSOP | PW | 16 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| CD74HC238PWR1G4 | TSSOP | PW | 16 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| CD74HCT138M96 | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |
| CD74HCT238M96 | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |
| CD74HCT238PWR | TSSOP | PW | 16 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| CD74HC138M96 | SOIC | D | 16 | 2500 | 353.0 | 353.0 | 32.0 |
| CD74HC138M96G4 | SOIC | D | 16 | 2500 | 353.0 | 353.0 | 32.0 |
| CD74HC238M96 | SOIC | D | 16 | 2500 | 340.5 | 336.1 | 32.0 |
| CD74HC238M96 | SOIC | D | 16 | 2500 | 340.5 | 336.1 | 32.0 |
| CD74HC238M961G4 | SOIC | D | 16 | 2500 | 353.0 | 353.0 | 32.0 |
| CD74HC238NSR | SOP | NS | 16 | 2000 | 353.0 | 353.0 | 32.0 |
| CD74HC238PWR | TSSOP | PW | 16 | 2000 | 356.0 | 356.0 | 35.0 |
| CD74HC238PWR1G4 | TSSOP | PW | 16 | 2000 | 356.0 | 356.0 | 35.0 |
| CD74HCT138M96 | SOIC | D | 16 | 2500 | 353.0 | 353.0 | 32.0 |
| CD74HCT238M96 | SOIC | D | 16 | 2500 | 353.0 | 353.0 | 32.0 |
| CD74HCT238PWR | TSSOP | PW | 16 | 2000 | 356.0 | 356.0 | 35.0 |

TUBE


*All dimensions are nominal

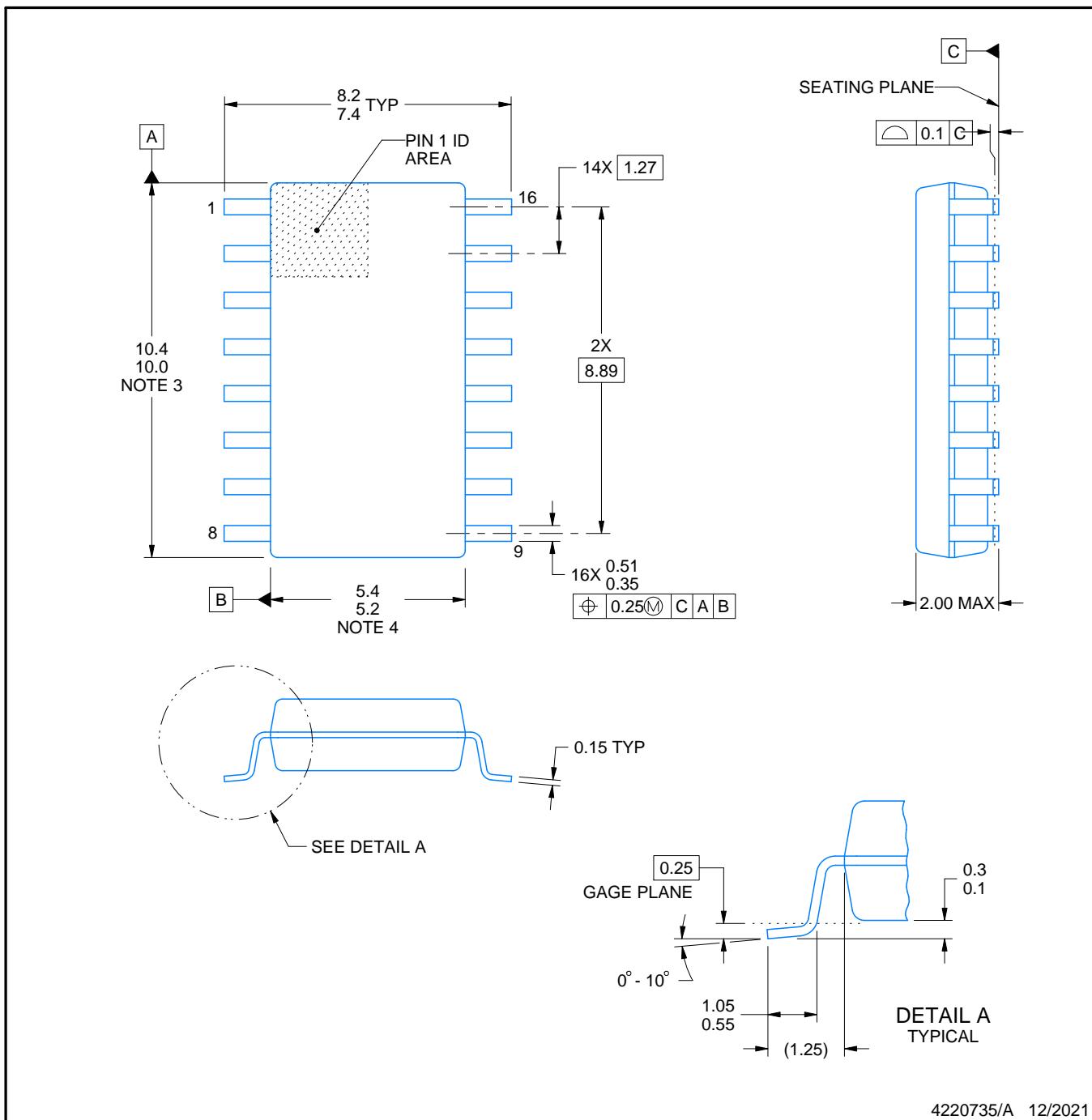
| Device | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | T (μm) | B (mm) |
|---------------|--------------|--------------|------|-----|--------|--------|--------|--------|
| CD74HC138E | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| CD74HC138E | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| CD74HC138E.A | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| CD74HC138E.A | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| CD74HC238E | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| CD74HC238E | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| CD74HC238E.A | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| CD74HC238E.A | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| CD74HC238EE4 | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| CD74HC238EE4 | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| CD74HCT138E | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| CD74HCT138E | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| CD74HCT138E.A | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| CD74HCT138E.A | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| CD74HCT238E | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| CD74HCT238E | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| CD74HCT238E.A | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |



PACKAGE OUTLINE

SOP - 2.00 mm max height

SOP



4220735/A 12/2021

NOTES:

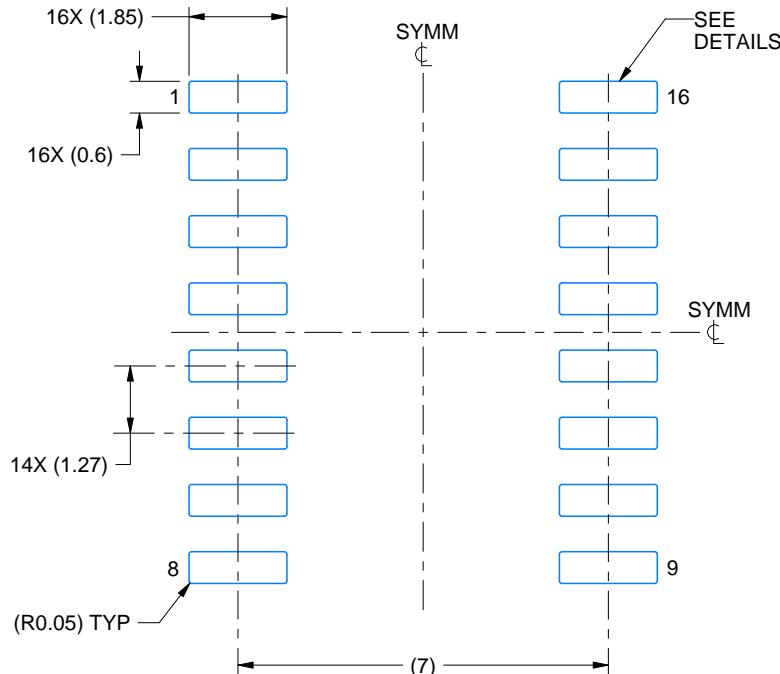
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.

EXAMPLE BOARD LAYOUT

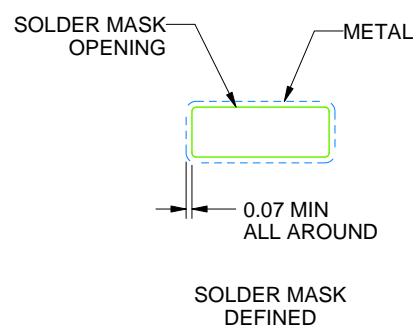
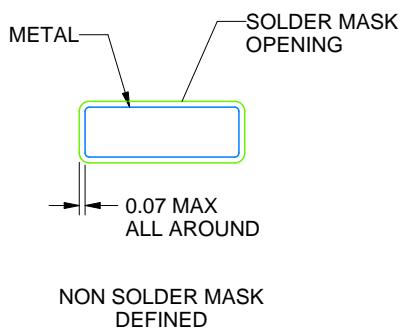
NS0016A

SOP - 2.00 mm max height

SOP



LAND PATTERN EXAMPLE
SCALE:7X



SOLDER MASK DETAILS

4220735/A 12/2021

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

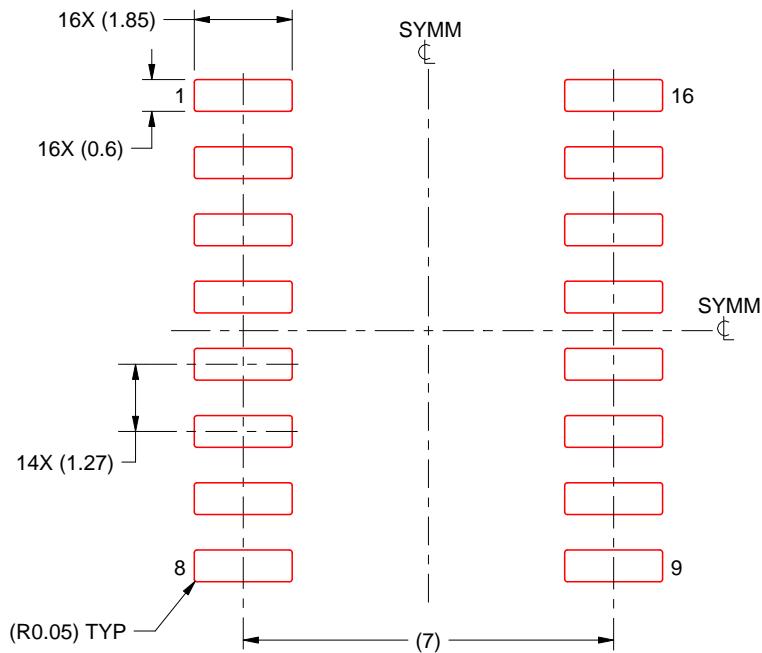
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

NS0016A

SOP - 2.00 mm max height

SOP



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:7X

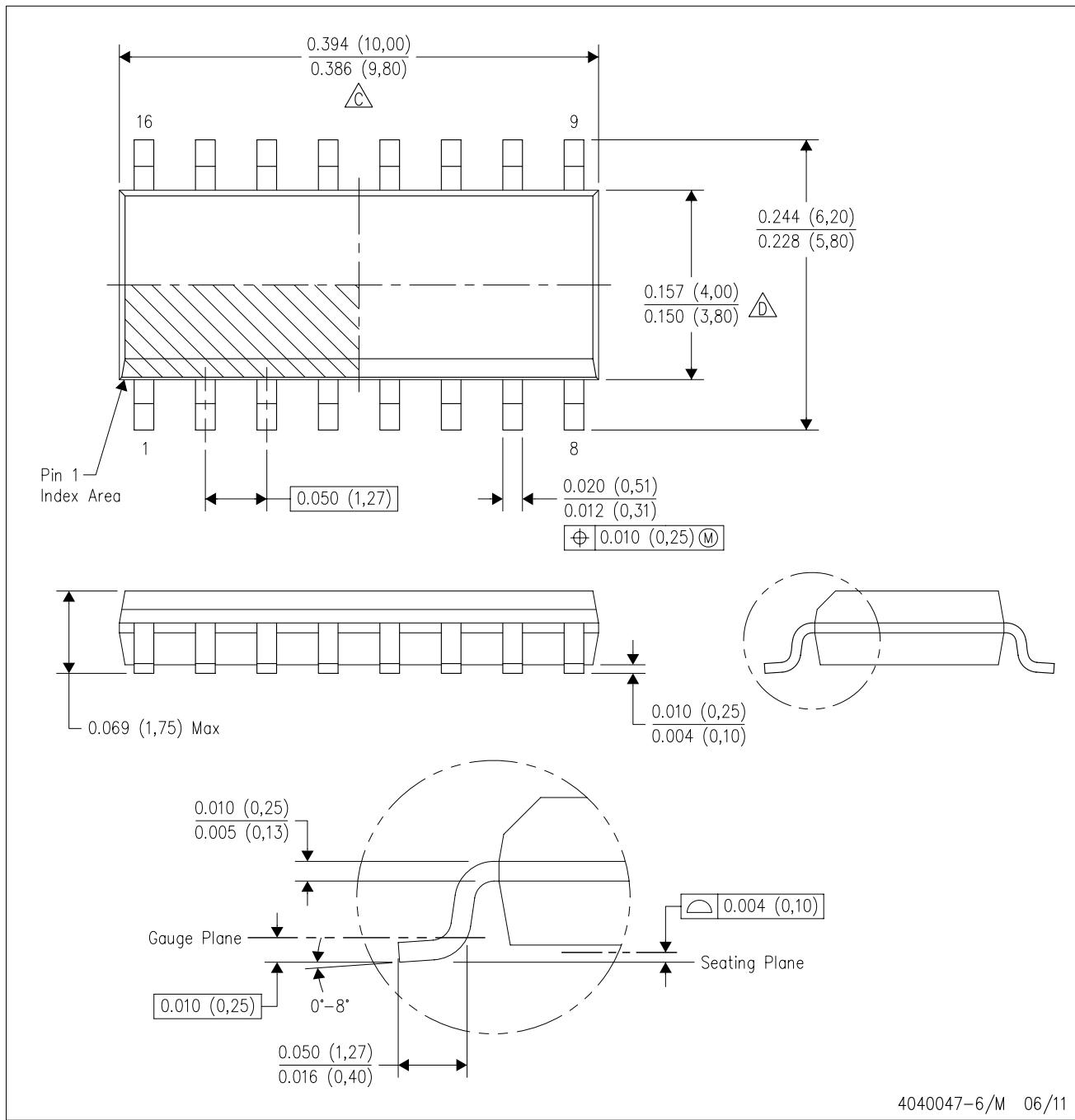
4220735/A 12/2021

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.

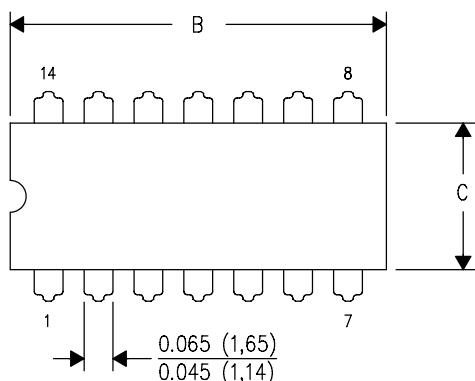
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.

E. Reference JEDEC MS-012 variation AC.

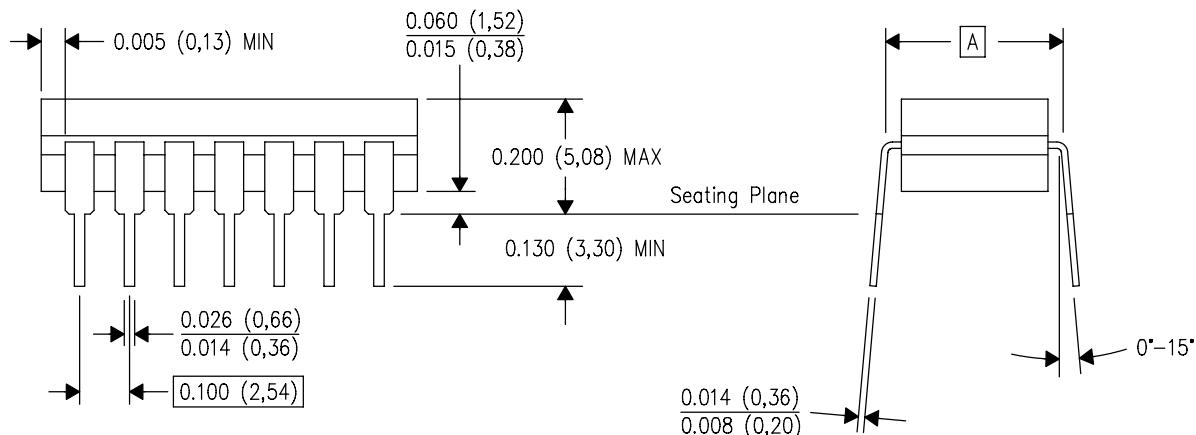
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



| PINS ** DIM | 14 | 16 | 18 | 20 |
|----------------|------------------------|------------------------|------------------------|------------------------|
| A | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC |
| B MAX | 0.785 (19,94) | .840 (21,34) | 0.960 (24,38) | 1.060 (26,92) |
| B MIN | — | — | — | — |
| C MAX | 0.300 (7,62) | 0.300 (7,62) | 0.310 (7,87) | 0.300 (7,62) |
| C MIN | 0.245 (6,22) | 0.245 (6,22) | 0.220 (5,59) | 0.245 (6,22) |



4040083/F 03/03

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

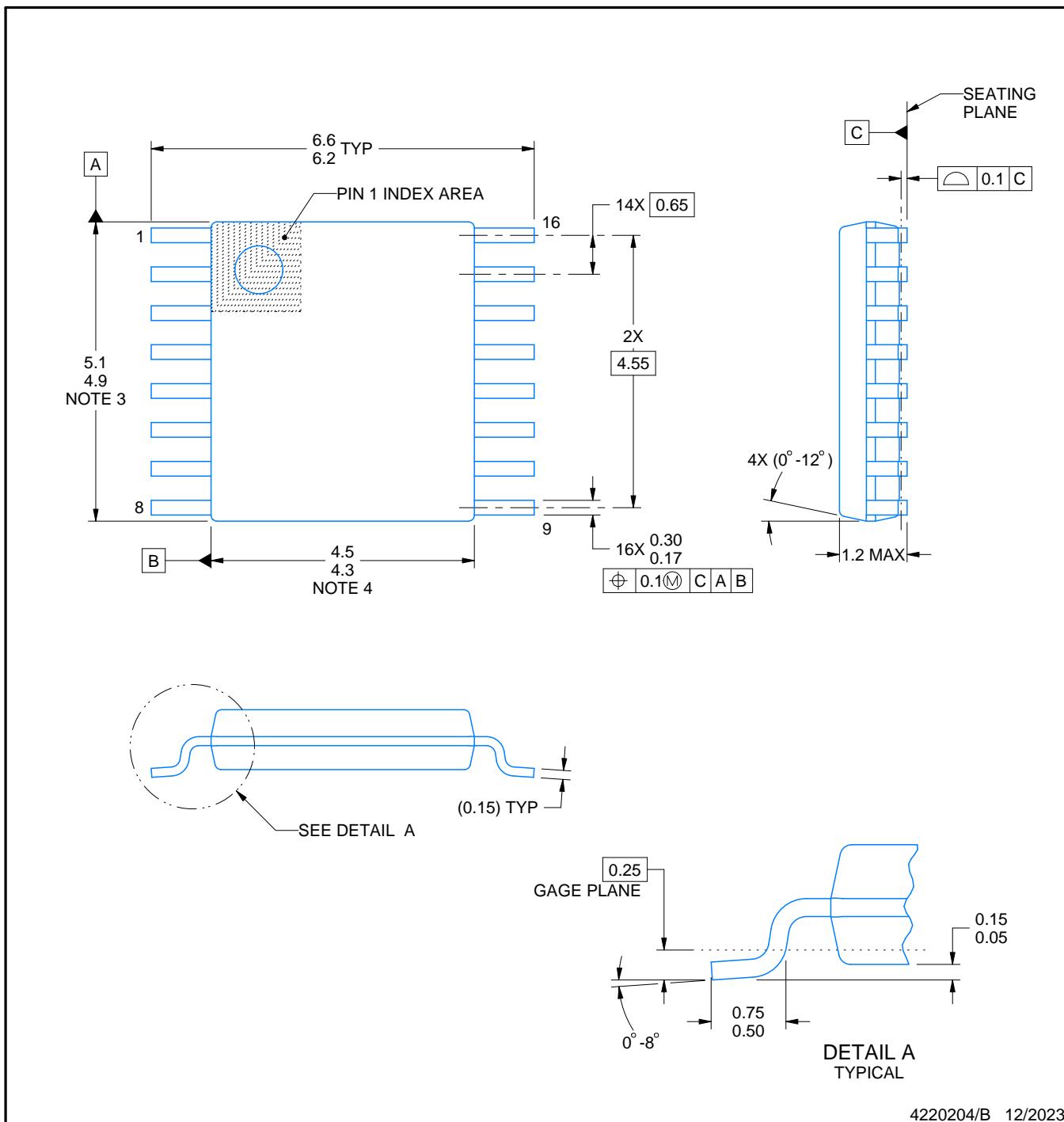
PACKAGE OUTLINE

PW0016A



TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

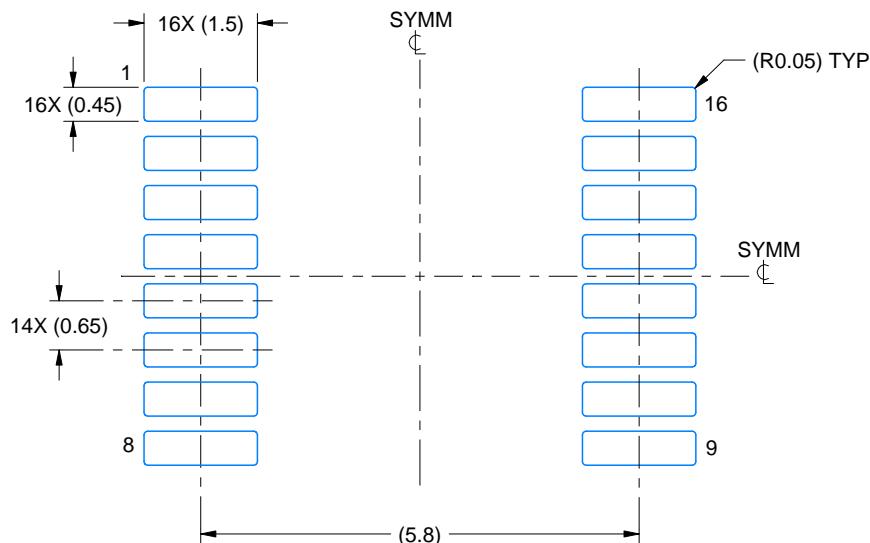
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

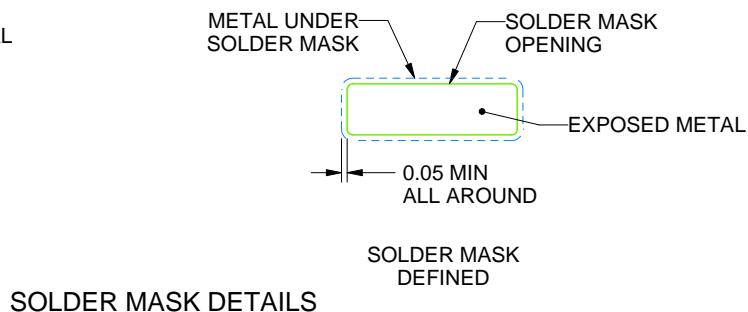
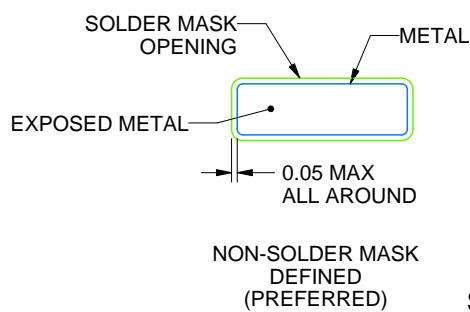
PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4220204/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

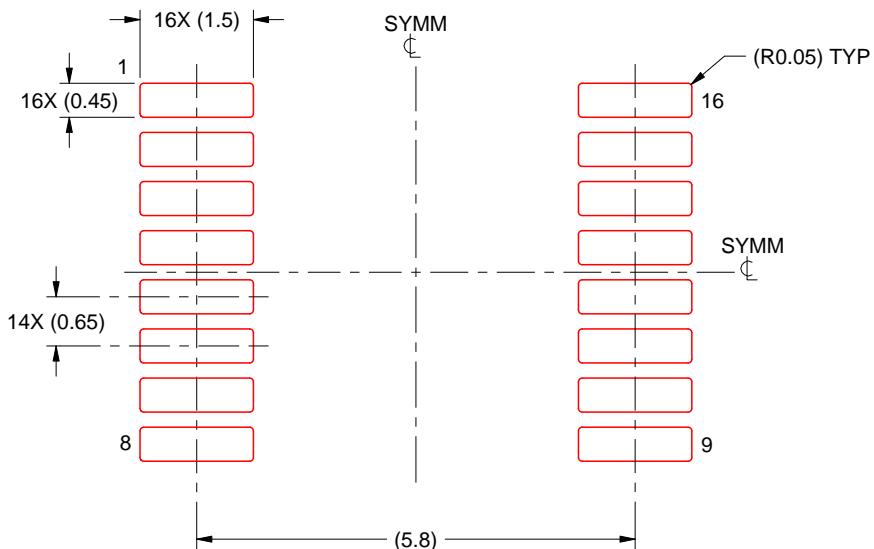
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/B 12/2023

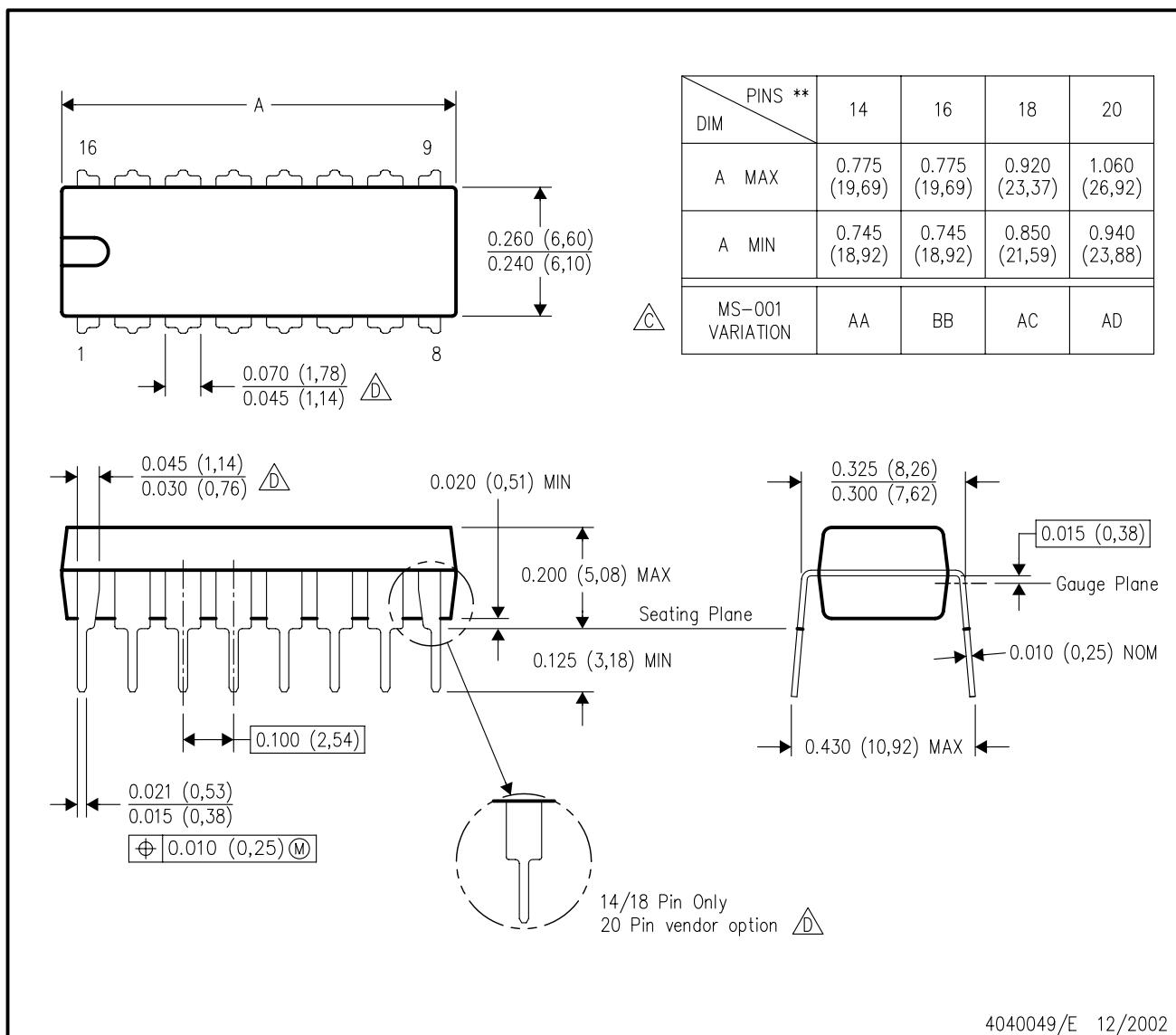
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.

△ Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

△ The 20 pin end lead shoulder width is a vendor option, either half or full width.

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